

100301

Low Power Triple 5-Input OR/NOR Gate

General Description

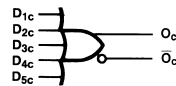
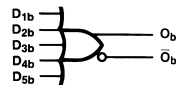
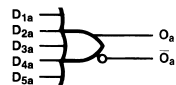
The 100301 is a monolithic triple 5-input OR/NOR gate. All inputs have 50 k Ω pull-down resistors and all outputs are buffered.

- 2000V ESD protection
- Pin/function compatible with 100101
- Voltage compensated operating range = -4.2V to -5.7V
- Standard Microcircuit Drawing (SMD) 5962-9152801

Features

- 23% power reduction of the 100101

Logic Symbol

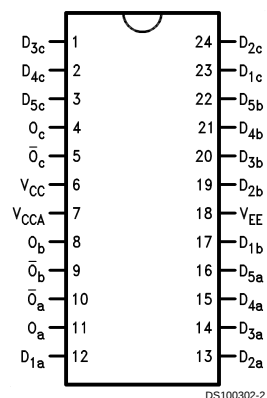


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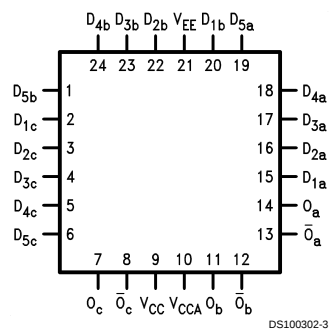
Pin Names	Description
D_{na}, D_{nb}, D_{nc}	Data Inputs
O_a, O_b, O_c	Data Outputs
$\bar{O}_a, \bar{O}_b, \bar{O}_c$	Complementary Data Outputs

Connection Diagrams

24-Pin DIP



24-Pin Quad Cerpak



Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Above which the useful life may be impaired

Storage Temperature (T_{STG}) -65°C to $+150^{\circ}\text{C}$

Maximum Junction Temperature (T_J)
Ceramic $+175^{\circ}\text{C}$

V_{EE} Pin Potential to

Ground Pin -7.0V to $+0.5\text{V}$

Input Voltage (DC) V_{EE} to $+0.5\text{V}$

Output Current (DC Output HIGH) -50 mA

ESD (Note 2)

$\geq 2000\text{V}$

Recommended Operating Conditions

Case Temperature (T_C)

Military -55°C to $+125^{\circ}\text{C}$

Supply Voltage (V_{EE}) -5.7V to -4.2V

Note 1: Absolute maximum ratings are those values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: ESD testing conforms to MIL-STD-883, Method 3015.

Military Version DC Electrical Characteristics

$V_{EE} = -4.2\text{V}$ to -5.7V , $V_{CC} = V_{CCA} = \text{GND}$, $T_C = -55^{\circ}\text{C}$ to $+125^{\circ}\text{C}$

Symbol	Parameter	Min	Max	Units	T_C	Conditions	Notes
V_{OH}	Output HIGH Voltage	-1025	-870	mV	0°C to $+125^{\circ}\text{C}$	$V_{IN} = V_{IH(\text{Max})}$ or $V_{IL}(\text{Min})$	Loading with 50Ω to -2.0V (Notes 3, 4, 5)
		-1085	-870	mV	-55°C		
V_{OL}	Output LOW Voltage	-1830	-1620	mV	0°C to $+125^{\circ}\text{C}$	$V_{IN} = V_{IH(\text{Min})}$ or $V_{IL}(\text{Max})$	Loading with 50Ω to -2.0V (Notes 3, 4, 5)
		-1830	-1555	mV	-55°C		
V_{OHC}	Output HIGH Voltage	-1035		mV	0°C to $+125^{\circ}\text{C}$	$V_{IN} = V_{IH(\text{Min})}$ or $V_{IL}(\text{Max})$	Loading with 50Ω to -2.0V (Notes 3, 4, 5)
V_{OLC}	Output LOW Voltage		-1610	mV	0°C to $+125^{\circ}\text{C}$		
			-1555	mV	-55°C		
V_{IH}	Input HIGH Voltage	-1165	-870	mV	-55°C to $+125^{\circ}\text{C}$	Guaranteed HIGH Signal for All Inputs	(Notes 3, 4, 5, 6)
V_{IL}	Input LOW Voltage	-1830	-1475	mV	-55°C to $+125^{\circ}\text{C}$	Guaranteed LOW Signal for All Inputs	(Notes 3, 4, 5, 6)
I_{IL}	Input LOW Current	0.50		μA	-55°C to $+125^{\circ}\text{C}$	$V_{EE} = -4.2\text{V}$ $V_{IN} = V_{IL(\text{Min})}$	(Notes 3, 4, 5)
I_{IH}	Input HIGH Current		240	μA	0°C to $+125^{\circ}\text{C}$	$V_{EE} = -5.7\text{V}$	(Notes 3, 4, 5)
			340	μA	-55°C	$V_{IN} = V_{IH}(\text{Max})$	
I_{EE}	Power Supply Current	-32	-12	mA	-55°C to $+125^{\circ}\text{C}$	Inputs Open	(Notes 3, 4, 5)

Note 3: F100K 300 Series cold temperature testing is performed by temperature soaking (to guarantee junction temperature equals -55°C), then testing immediately without allowing for the junction temperature to stabilize due to heat dissipation after power-up. This provides "cold start" specs which can be considered a worst case condition at cold temperatures.

Note 4: Screen tested 100% on each device at -55°C , $+25^{\circ}\text{C}$, and $+125^{\circ}\text{C}$, Subgroups 1, 2, 3, 7, and 8.

Note 5: Sample tested (Method 5005, Table I) on each manufactured lot at -55°C , $+25^{\circ}\text{C}$, and $+125^{\circ}\text{C}$, Subgroups A1, 2, 3, 7, and 8.

Note 6: Guaranteed by applying specified input condition and testing V_{OH}/V_{OL} .

AC Electrical Characteristics

$V_{EE} = -4.2\text{V}$ to -5.7V , $V_{CC} = V_{CCA} = \text{GND}$

Symbol	Parameter	$T_C = -55^{\circ}\text{C}$		$T_C = +25^{\circ}\text{C}$		$T_C = +125^{\circ}\text{C}$		Units	Conditions	Notes
		Min	Max	Min	Max	Min	Max			
t_{PLH}	Propagation Delay	0.25	1.70	0.30	1.50	0.30	1.80	ns	Figures 1, 2	(Notes 7, 8, 9, 11)
t_{PHL}	Data to Output									
t_{TLH}	Transition Time	0.30	1.20	0.30	1.20	0.30	1.20	ns		(Note 10)
t_{THL}	20% to 80%, 80% to 20%									

Note 7: F100K 300 Series cold temperature testing is performed by temperature soaking (to guarantee junction temperature equals -55°C), then testing immediately after power-up. This provides "cold start" specs which can be considered a worst case condition at cold temperatures.

Note 8: Screen tested 100% on each device at $+25^{\circ}\text{C}$ temperature only, Subgroup A9.

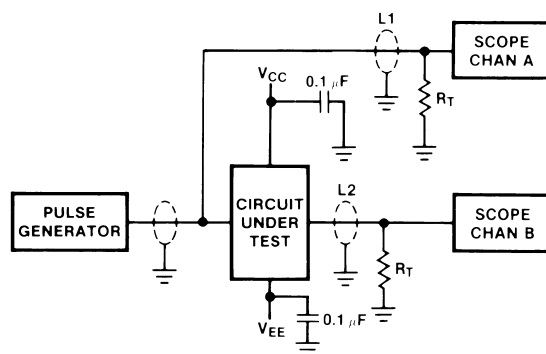
Note 9: Sample tested (Method 5005, Table I) on each manufactured lot at $+25^{\circ}\text{C}$, Subgroup A9, and at $+125^{\circ}\text{C}$ and -55°C temperatures, Subgroups A10 and A11.

AC Electrical Characteristics (Continued)

Note 10: Not tested at +25°C, +125°C, and -55°C temperature (design characterization data).

Note 11: The propagation delay specified is for single output switching. Delays may vary up to 100 ps with multiple outputs switching.

Test Circuitry



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Notes:

$V_{CC}, V_{CCA} = +2V, V_{EE} = -2.5V$

L1 and L2 = equal length 50Ω impedance lines

$R_T = 50\Omega$ terminator internal to scope

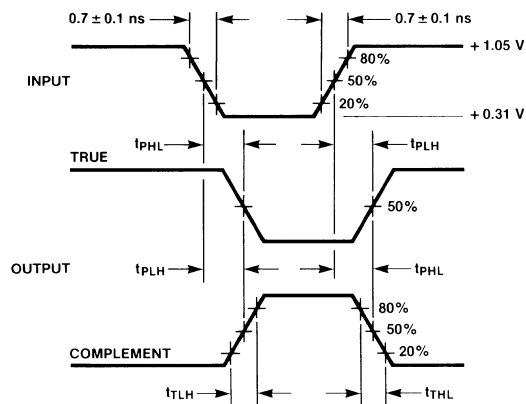
Decoupling 0.1 μF from GND to V_{CC} and V_{EE}

All unused outputs are loaded with 50Ω to GND

C_L = Fixture and stray capacitance ≤ 3 pF

FIGURE 1. AC Test Circuit

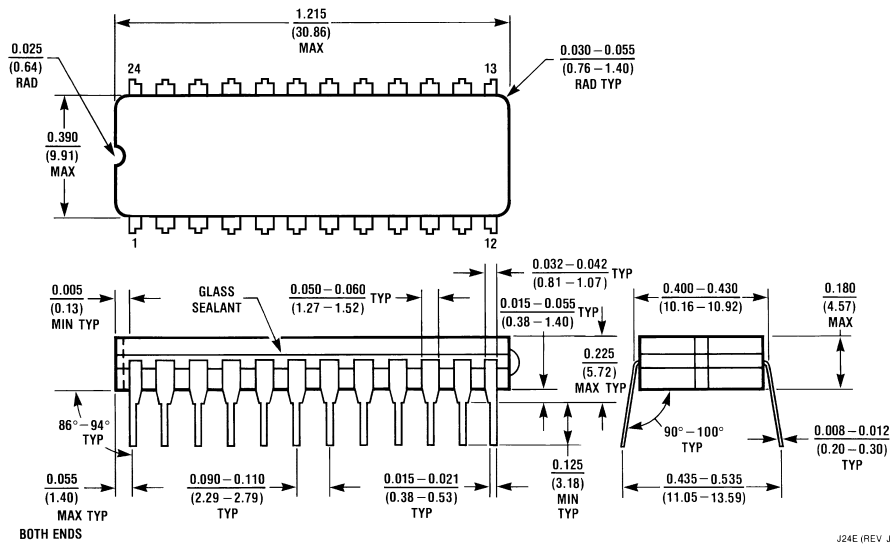
Switching Waveforms



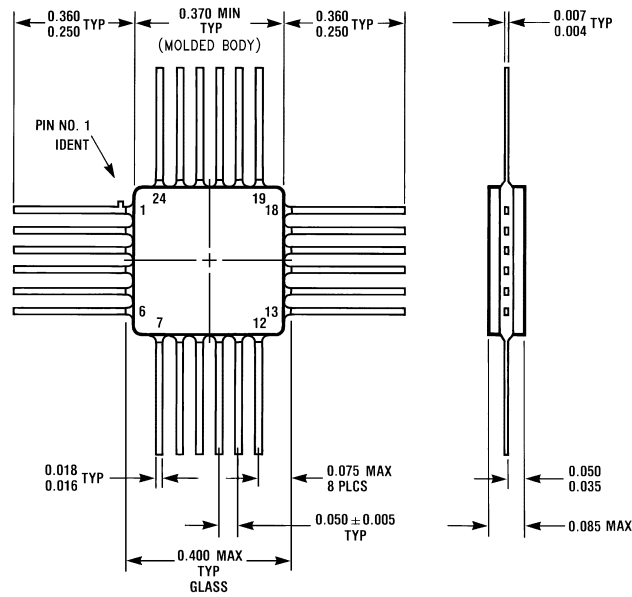
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FIGURE 2. Propagation Delay and Transition Times

Physical Dimensions inches (millimeters) unless otherwise noted



24-Lead Ceramic Dual-In-Line Package (0.400" Wide) (D)
NS Package Number J24E



24-Lead Quad Cerpak (F)
NS Package Number W24B

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